

What is claimed is:

1. A multi-layer board comprising:

a ceramic layer;

a first resin layer over said ceramic layer; and

5 a first impedance element formed on said ceramic layer.

2. The multi-layer board of claim 1, wherein said first resin layer is provided with an electronic component mounted thereon.

10 3. The multi-layer board of claim 1, further comprising a second resin layer over said ceramic layer, said second resin layer being disposed at an opposite side of said first resin layer about said ceramic layer.

15 4. The multi-layer board of claim 3, further comprising a strip line formed on said second resin layer.

5. The multi-layer board of claim 3, further comprising a third resin layer over said first resin layer.

20 6. The multi-layer board of claim 5, further comprising a strip line formed on said third resin layer.

7. The multi-layer board of claim 5, wherein said third resin layer is provided with an electronic component mounted thereon.

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8. The multi-layer board of claim 5, further comprising a fourth resin layer between said first and third resin layers.

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9. The multi-layer board of claim 5, further comprising:  
a polyimide film between said first and third resin layers; and  
a capacitor formed on said polyimide film.

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10. The multi-layer board of claim 1, wherein said first impedance  
element is a patterned inductor.

11. The multi-layer board of claim 10, wherein said patterned  
inductor is laser-trimmed.

12. The multi-layer board of claim 10, further comprising a ground  
pattern formed on said first resin layer excluding a portion corresponding to  
said patterned inductor, said ground pattern being formed at an opposite side  
to said ceramic layer.

13. The multi-layer board of claim 1, wherein said first impedance  
element is a capacitor.

14. The multi-layer board of claim 1, wherein said first impedance  
element is a resistor.

15. The multi-layer board of claim 14, wherein said resistor is  
laser-trimmed.

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16. The multi-layer board of claim 1, further comprising a second  
impedance element formed on said ceramic layer at an opposite side to said

first impedance element.

17. The multi-layer board of claim 1, further comprising a strip line formed on said first resin layer.